Unit: mm

TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π -MOSVI)

2SK3934

Switching Regulator Applications

• Low drain-source ON resistance: RDS (ON) = 0.23Ω (typ.)

• High forward transfer admittance: $|Y_{fs}| = 8.2 \text{ S (typ.)}$

• Low leakage current: $IDSS = 100 \mu A (VDS = 500 V)$

• Enhancement model: $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characte	eristic	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	500	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	500	V	
Gate-source voltage		V _{GSS}	±30	V	
	DC (Note 1)	ID	15	А	
Drain current	Pulse (t = 1 ms) (Note 1)	I _{DP}	60		
Drain power dissipat	ion (Tc = 25°C)	P _D	50	W	
Single pulse avalanche energy (Note 2)		E _{AS}	1.08	J	
Avalanche current		I _{AR}	15	А	
Repetitive avalanche energy (Note 3)		E _{AR}	5.0	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

1.14±0.15 0.69±0.15 1.2 3 0.69±0.15 1.3 Gate 2.54 2.54 1.4 Gate 2.5 Drain 3.5 Source JEDEC JEITA SC-67 TOSHIBA 2.7±0.2

Weight: 1.7 g (typ.)

Thermal Characteristics

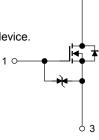
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.5	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C during use of the device.

Note 2: V_{DD} = 90 V, T_{Ch} = 25°C (initial), L = 8.16mH, I_{AR} = 15 A, R_G = 25 Ω

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



Ω

Electrical Characteristics (Ta = 25°C)

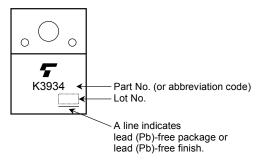
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Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Gate-source breakdown voltage V		V (BR) GSS	$I_G=\pm 10~\mu A,~V_{DS}=0~V$	±30	_	_	V
Drain cutoff curre	ent	I _{DSS}			100	μΑ	
Drain-source brea	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	500	_	_	V
Gate threshold voltage		V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 10 V, I _D = 7.5 A	_	0.23	0.3	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 7.5 A	2.3	8.2	_	S
Input capacitance	ut capacitance C _{iss}			_	3100	_	
Reverse transfer capacitance		C _{rss}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		20	_	pF
Output capacitance		Coss		_	270	_	
	Rise time	t _r	$\begin{array}{c c} 10 \text{ V} & I_D = 7.5 \text{ A} & V_{OUT} \\ \hline V_{GS} & V & & & \\ \hline 50 \Omega & & & \\ \hline $		70		. ns
Switching time	Turn-on time	t _{on}			130		
Switching time	Fall time	t _f			70		
	Turn-off time	t _{off}			280		
Total gate charge		Qg		_	62	_	
Gate-source charge		Q _{gs}	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$		40		nC
Gate-drain charge		Q _{gd}		_	22	_	

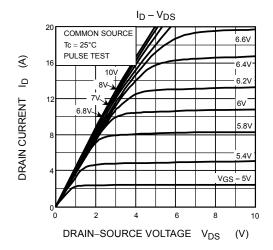
Source-Drain Ratings and Characteristics (Ta = 25°C)

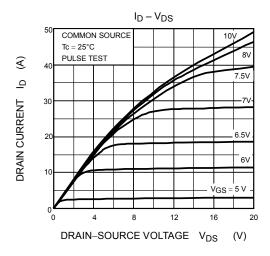
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current	(Note 1)	I _{DR}	_	-	_	15	Α
Pulse drain reverse current	(Note 1)	I _{DRP}	_	_	_	60	Α
Forward voltage (diode)		V_{DSF}	$I_{DR} = 15 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse recovery time		t _{rr}	$I_{DR} = 15 \text{ A}, V_{GS} = 0 \text{ V},$	_	1.3	_	μS
Reverse recovery charge		Q _{rr}	dI _{DR} /dt = 100 A/μs	_	18	_	μС

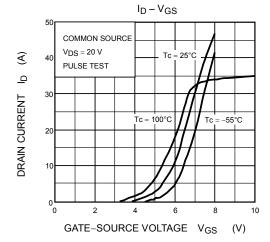
Marking

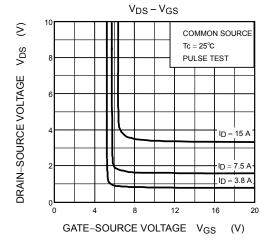


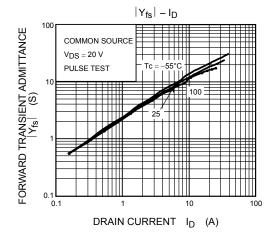
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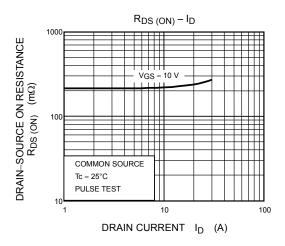


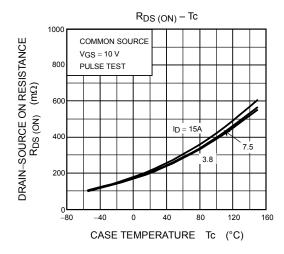


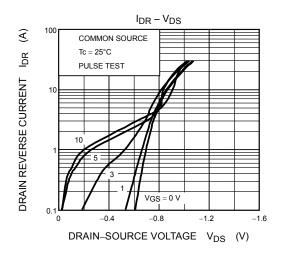


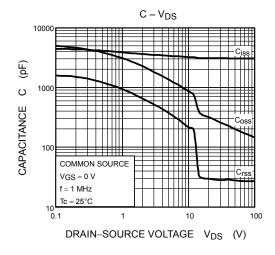


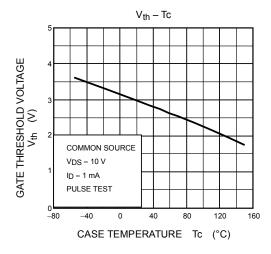


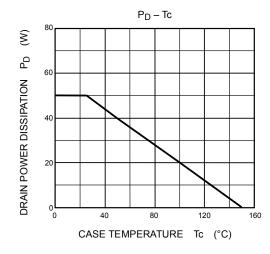


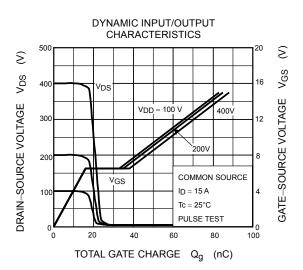


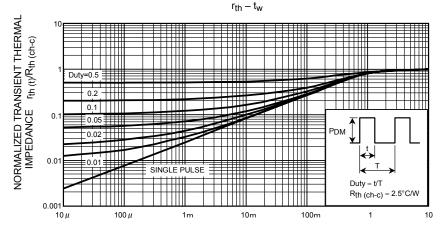




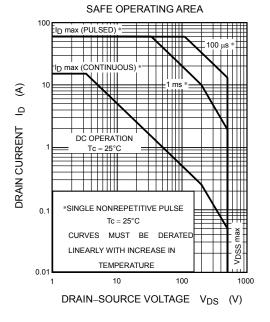


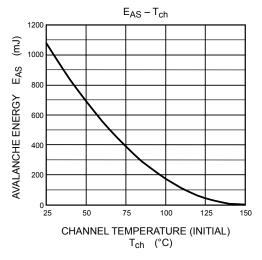


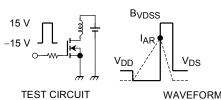




PULSE WIDTH t_{W} (s)







$$R_G = 25~\Omega$$

$$V_{DD} = 90~V,~L = 8.13~mH$$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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